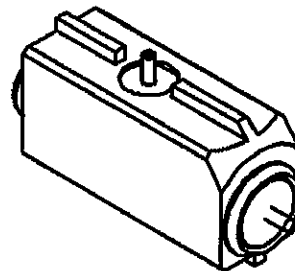
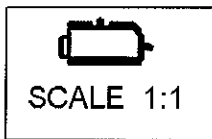
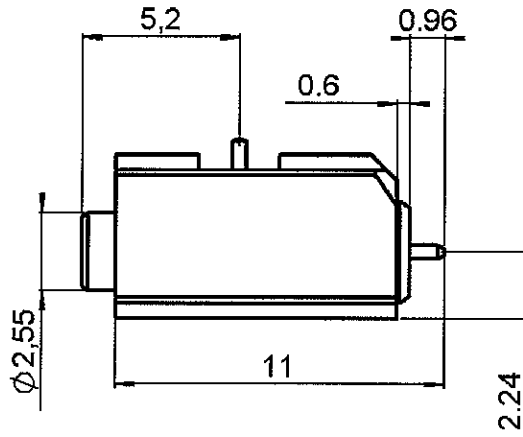
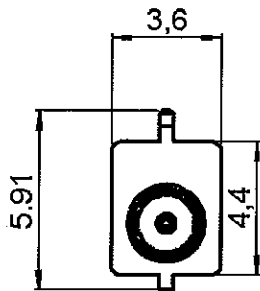


REEL OF 500 SMT SWITCH RECEPTACLE

R199.005.880

EDGE-CARD

Series : MC-CARD



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 0.8 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	POLYETHER ETHERCETONE 30% GF	-
GASKET	-	-
OTHERS PARTS	STAINLESS STEEL	-
-	-	-
-	-	-

Issue : 0541 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL OF 500 SMT SWITCH RECEPTACLE

R199.005.880

EDGE-CARD

Series : MC-CARD

PACKAGING

SPECIFICATION

Standard	Unit	Other
500	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance		50 Ω
Frequency		0-3 GHz
VSWR	1.4* +	0.000 x F(GHz) Maxi
Insertion loss		0.3** √F(GHz) dB Maxi
RF leakage	- (- F(GHz)) dB Maxi
Voltage rating		100 Veff Maxi
Dielectric withstanding voltage		250 Veff mini
Insulation resistance		5000 MΩ mini

Operating temperature	-40/+110 °C
Hermetic seal	Atm.cm3/s
Panel leakage	

OTHERS CHARACTERISTICS

Assembly instruction **NA**

Others :

*1.4 max at 2.5 GHz.00

**Isol between 2ways:-22dBmin at 2.5GHz

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end		N mini
Axial force – Opposite end		N mini
Torque		N.cm mini

Recommended torque		
Mating		N.cm
Panel nut		N.cm

Mating life	5000	Cycles mini
Weight	0.985	g

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REEL OF 500 SMT SWITCH RECEPTACLE

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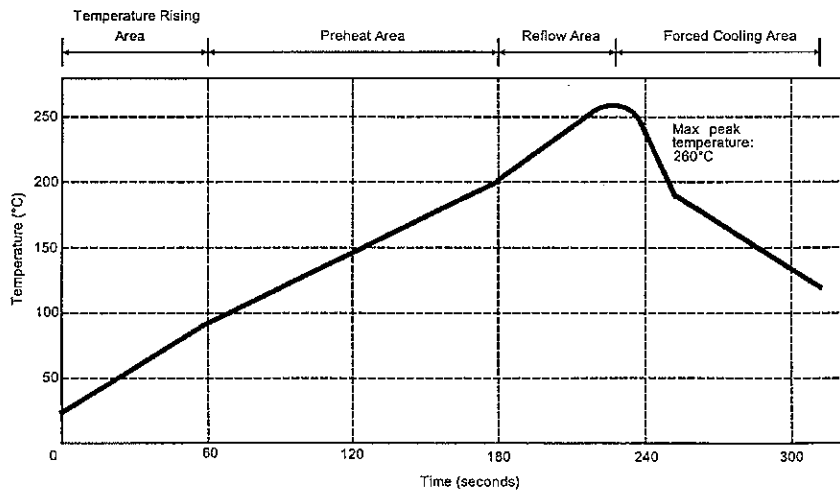
EDGE-CARD

Series : MC-CARD

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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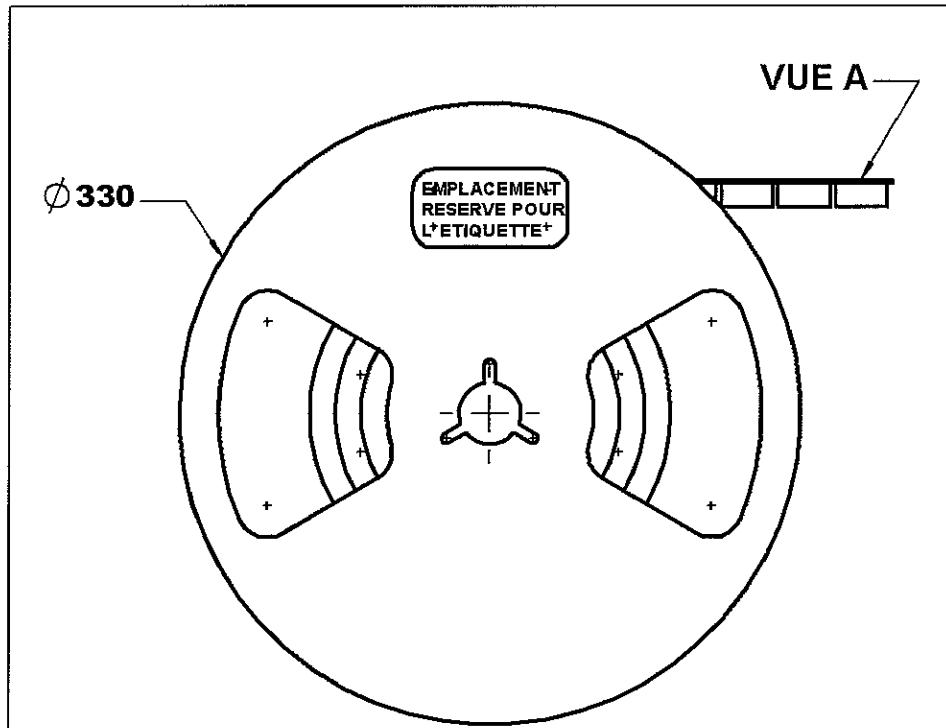
REEL OF 500 SMT SWITCH RECEPTACLE

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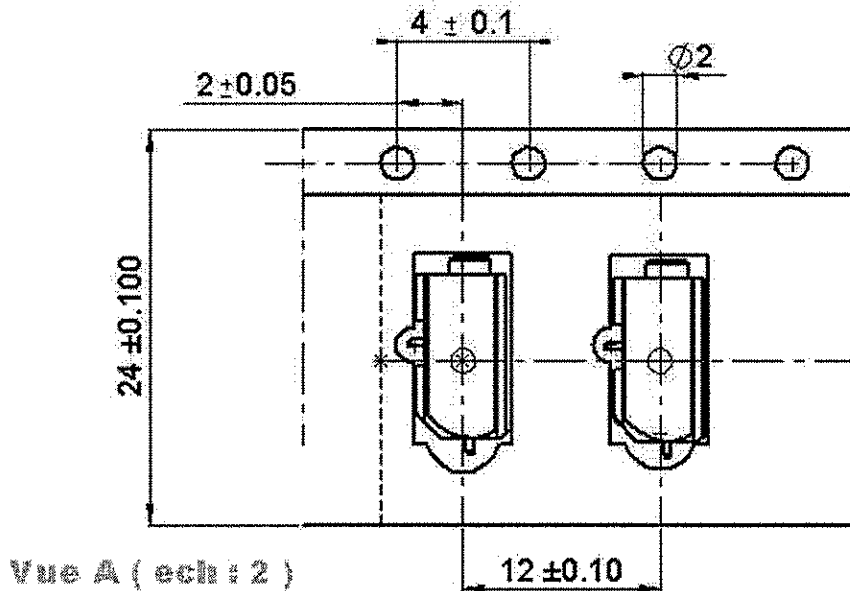
EDGE-CARD

Series : MC-CARD

PACKAGING



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Issue : 0541 D

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